

### **Data Sheet**

## LC<sup>2</sup>MOS Quad SPST Switches

## ADG441/ADG442/ADG444

#### **FEATURES**

44 V supply maximum ratings  $V_{SS}$  to  $V_{DD}$  analog signal range Low on resistance (<70  $\Omega$ ) Low  $\Delta R_{ON}$  (9  $\Omega$  max) Low  $R_{ON}$  match (3  $\Omega$  max) Low power dissipation Fast switching times  $t_{ON}$  < 110 ns

t<sub>on</sub> < 110 ns t<sub>off</sub> < 60 ns

Low leakage currents (3 nA max)
Low charge injection (6 pC max)
Break-before-make switching action
Latch-up proof A grade
Plug-in upgrade for DG201A/ADG201A, DG202A/ADG202A,
DG211/ADG211A
Plug-in replacement for DG441/DG442/DG444

#### **APPLICATIONS**

Audio and video switching Automatic test equipment Precision data acquisition Battery-powered systems Sample-and-hold systems Communication systems

#### **GENERAL DESCRIPTION**

The ADG441, ADG442, and ADG444 are monolithic CMOS devices that comprise of four independently selectable switches. They are designed on an enhanced LC<sup>2</sup>MOS process that provides low power dissipation yet gives high switching speed and low on resistance.

The on resistance profile is very flat over the full analog input range, which ensures good linearity and low distortion when switching audio signals. High switching speed also makes the parts suitable for video signal switching. CMOS construction ensures ultralow power dissipation, making the parts ideally suited for portable and battery-powered instruments. The ADG441, ADG442, and ADG444 contain four independent SPST switches. Each switch of the ADG441 and ADG444 turns on when a logic low is applied to the appropriate control input. The ADG442 switches are turned on with logic high on the appropriate control input. The ADG441 and ADG444 switches differ in that the ADG444 requires a 5 V logic power supply that is applied to the  $V_{\rm L}$  pin. The ADG441 and ADG442 do not have a  $V_{\rm L}$  pin, the logic power supply is generated internally by an on-chip voltage generator.

Rev. B

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#### **FUNCTIONAL BLOCK DIAGRAM**

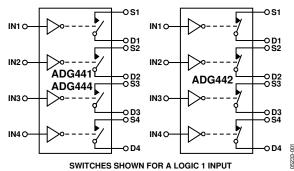


Figure 1.

Each switch conducts equally well in both directions when ON and has an input signal range that extends to the power supplies. In the OFF condition, signal levels up to the supplies are blocked. All switches exhibit break-before-make switching action for use in multiplexer applications. Inherent in the design is the low charge injection for minimum transients when switching the digital inputs.

#### **PRODUCT HIGHLIGHTS**

- Extended signal range. The ADG441A/ADG442A/ ADG444A are fabricated on an enhanced LC<sup>2</sup>MOS, trench-isolated process, giving an increased signal range that extends to the supply rails.
- 2. Low power dissipation.
- 3. Low Ron.
- 4. Trench isolation guards against latch-up for A grade parts. A dielectric trench separates the P and N channel transistors thereby preventing latch-up even under severe overvoltage conditions.
- Break-before-make switching. This prevents channel shorting when the switches are configured as a multiplexer.
- 6. Single-supply operation. For applications where the analog signal is unipolar, the ADG441/ADG442/ADG444 can be operated from a single-rail power supply. The parts are fully specified with a single 12 V power supply.

# **Data Sheet**

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Updated Outline Dimensions	
5/05—Rev. 0 to Rev. A	
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### **SPECIFICATIONS**

### **DUAL SUPPLY**<sup>1</sup>

 $V_{DD}$  = +15 V  $\pm$  10%,  $V_{SS}$  = -15 V  $\pm$  10%,  $V_{L}$  = +5 V  $\pm$  10% (ADG444), GND = 0 V, unless otherwise noted.

Table 1.

	B Version				
Parameter	+25°C	-40°C to +85°C	Unit	Test Conditions/Comments	
ANALOG SWITCH					
Analog Signal Range		$V_{SS}$ to $V_{DD}$	V		
Ron	40		Ω typ	$V_D = \pm 8.5 \text{ V}, I_S = -10 \text{ mA}$	
	70	85	Ω max	$V_{DD} = +13.5 \text{ V}, V_{SS} = -13.5 \text{ V}$	
ΔRon		4	Ωtyp	$-8.5 \text{ V} \le \text{V}_{D} \le +8.5 \text{ V}$	
		9	Ω max		
R <sub>ON</sub> Match		1	Ωtyp	$V_D = 0 \text{ V, I}_S = -10 \text{ mA}$	
NON WATER		3	Ω max	15 0 17 15 10 11 11	
LEAKAGE CURRENTS			1211167	$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$	
Source OFF Leakage I <sub>s</sub> (OFF)	±0.01		nA typ	·	
Source of Fredunge 15 (of F)				$V_D = \pm 15.5 \text{ V}, V_S = \mp 15.5 \text{ V}$	
	±0.5	±3	nA max	See Figure 15	
Drain OFF Leakage I <sub>D</sub> (OFF)	±0.01		nA typ	$V_D = \pm 15.5 \text{ V}, V_S = \mp 15.5 \text{ V}$	
	±0.5	±3	nA max	See Figure 15	
Channel ON Leakage ID, Is (ON)	±0.08		nA typ	$V_S = V_D = \pm 15.5 \text{ V}$	
	±0.5	±3	nA max	See Figure 16	
DIGITAL INPUTS					
Input High Voltage, V <sub>INH</sub>		2.4	V min		
Input Low Voltage, V <sub>INL</sub>		0.8	V max		
Input Current					
Int or Inh		±0.00001	μA typ	$V_{IN} = V_{INL}$ or $V_{INH}$	
THE COUNTY		±0.5	μA max		
DYNAMIC CHARACTERISTICS <sup>2</sup>			<b>P</b>		
ton	85		ns typ	$R_L = 1 \text{ k}\Omega$ , $C_L = 35 \text{ pF}$ ;	
CON	110	170	ns max	$V_s = \pm 10 \text{ V}$ ; see Figure 17	
toff	45	170	ns typ	$R_L = 1 \text{ k}\Omega$ , $C_L = 35 \text{ pF}$ ;	
COFF	60	80	ns max	$V_s = \pm 10 \text{ V}$ ; see Figure 17	
topen	30	00	ns typ	$R_L = 1 \text{ k}\Omega$ , $C_L = 35 \text{ pF}$ ;	
Charge Injection	1		pC typ	$V_S = 0 \text{ V}, R_S = 0 \Omega, C_L = 1 \text{ nF};$	
Charge injection	6		pC typ pC max	$V_{DD} = +15 \text{ V}, V_{SS} = -15 \text{ V}; \text{ see Figure 18}$	
OFF Isolation	60			$R_L = 50 \Omega$ , $C_L = 5 pF$ ; $f = 1 MHz$ ; see Figure 19	
Channel-to-Channel Crosstalk	100		dB typ	$R_L = 50 \Omega$ , $C_L = 5 \text{ pF}$ ; $I = 1 \text{ MHz}$ ; see Figure 19 $R_L = 50 \Omega$ , $C_L = 5 \text{ pF}$ ; $I = 1 \text{ MHz}$ ; see Figure 20	
			dB typ	f = 1  MHz	
C <sub>s</sub> (OFF)	4		pF typ		
C <sub>D</sub> (OFF)	4		pF typ	f = 1 MHz	
C <sub>D</sub> , C <sub>S</sub> (ON)	16		pF typ	f = 1 MHz	
POWER REQUIREMENTS				$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$	
I <sub>DD</sub>			_	Digital Inputs = 0 V or 5 V	
ADG441/ADG442		80	μA max		
ADG444	0.001		μA typ		
	1	2.5	μA max		
Iss	0.0001		μA typ		
	1	2.5	μA max		
I∟ (ADG444 Only)	0.001		μA typ	$V_L = 5.5 \text{ V}$	
	1	2.5	μA max		

<sup>&</sup>lt;sup>1</sup> Temperature range is: B Version: –40°C to +85°C.

<sup>&</sup>lt;sup>2</sup> Guaranteed by design, not subject to production test.

#### SINGLE SUPPLY<sup>1</sup>

 $V_{DD}$  = +12 V  $\pm$  10%,  $V_{SS}$  = 0 V,  $V_{L}$  = +5 V  $\pm$  10% (ADG444), GND = 0 V, unless otherwise noted.

Table 2.

		B Version			
Parameter	+25°C	-40°C to +85°C	Unit	Test Conditions/Comments	
ANALOG SWITCH					
Analog Signal Range		$0$ to $V_{\text{DD}}$	V		
Ron	70		Ω typ	$V_D = +3 V$ , $+8 V$ , $I_S = -5 mA$	
	110	130	Ωmax	$V_{DD} = 10.8 V$	
$\Delta R_{ON}$		4	Ω typ	$3 \text{ V} \leq \text{V}_D \leq 8 \text{ V}$	
		9	Ωmax		
Ron Match		1	Ω typ	$V_D = +6 \text{ V}, I_S = -5 \text{ mA}$	
		3	Ω max		
LEAKAGE CURRENT				$V_{DD} = 13.2 \text{ V}$	
Source OFF Leakage Is (OFF)	±0.01		nA typ	$V_D = 12.2 \text{ V}/1 \text{ V}, V_S = 1 \text{ V}/12.2 \text{ V}$	
_	±0.5	±3	nA max	See Figure 15	
Drain OFF Leakage I <sub>D</sub> (OFF)	±0.01		nA typ	$V_D = 12.2 \text{ V}/1 \text{ V}, V_S = 1 \text{ V}/12.2 \text{ V}$	
-	±0.5	±3	nA max	See Figure 15	
Channel ON Leakage ID, Is (ON)	±0.08		nA typ	$V_S = V_D = 12.2 \text{ V/1 V}$	
	±0.5	±3	nA max	Figure 16	
DIGITAL INPUTS					
Input High Voltage, V <sub>INH</sub>		2.4	V min		
Input Low Voltage, V <sub>INL</sub>		0.8	V max		
Input Current					
linl or linh		±0.00001	μA typ	$V_{IN} = V_{INL}$ or $V_{INH}$	
		±0.5	μA max		
DYNAMIC CHARACTERISTICS <sup>2</sup>					
ton	105		ns typ	$R_L = 1 \text{ k}\Omega$ , $C_L = 35 \text{ pF}$	
	150	220	ns max	$V_S = 8 \text{ V}$ ; Figure 17	
toff	40		ns typ	$R_L = 1 \text{ k}\Omega$ , $C_L = 35 \text{ pF}$	
	60	100	ns max	$V_S = 8 \text{ V}$ ; Figure 17	
topen	50		ns typ	$R_L = 1 \text{ k}\Omega$ , $C_L = 35 \text{ pF}$	
Charge Injection	2		pC typ	$V_S = 6 \text{ V}, R_S = 0 \Omega, C_L = 1 \text{ nF}$	
- ,	6		pC max	$V_{DD} = 12 \text{ V}, V_{SS} = 0 \text{ V}; \text{ see Figure 18}$	
OFF Isolation	60		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ; see Figure 19	
Channel-to-Channel Crosstalk	100		dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ; see Figure 20	
C <sub>s</sub> (OFF)	7		pF typ	f = 1 MHz	
C <sub>D</sub> (OFF)	10		pF typ	f = 1 MHz	
$C_D, C_S$ (ON)	16		pF typ	f = 1 MHz	
POWER REQUIREMENTS				V <sub>DD</sub> = 13.2 V	
I <sub>DD</sub>				Digital Inputs = 0 V or 5 V	
ADG441/ADG442		80	μA max		
ADG444	0.001		μA typ		
	1	2.5	μA max		
I <sub>L</sub> (ADG444 Only)	0.001		μA typ	$V_L = 5.5 \text{ V}$	
	1	2.5	μA max		

 $<sup>^1</sup>$  Temperature range is: B Version:  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ .  $^2$  Guaranteed by design, not subject to production test.

### **ABSOLUTE MAXIMUM RATINGS**

 $T_A = 25$ °C unless otherwise noted.

#### Table 3.

Table 5.	
Parameter	Rating
V <sub>DD</sub> to V <sub>SS</sub>	44 V
V <sub>DD</sub> to GND	-0.3 V to +25 V
V <sub>SS</sub> to GND	+0.3 V to −25 V
V <sub>L</sub> to GND	$-0.3$ V to $V_{DD}$ + $0.3$ V
Analog, Digital Inputs	$V_{SS} - 2V$ to $V_{DD} + 2V$ or 30 mA, Whichever Occurs First
Continuous Current, S or D	30 mA
Peak Current, S or D (Pulsed at 1 ms, 10% Duty Cycle Max)	100 mA
• •	
Operating Temperature Range	
Industrial (B Version)	−40°C to +85°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
Lead Temperature, Soldering (10 sec)	300°C
Plastic Package, Power Dissipation	470 mW
$\theta_{ exttt{JA}}$ , Thermal Impedance	177°C/W
Lead Temperature, Soldering (10 sec)	260°C
SOIC Package, Power Dissipation	600 mW
$\theta_{ exttt{JA}}$ , Thermal Impedance	77°C/W
Lead Temperature, Soldering	
Vapor Phase (60 sec)	215°C
Infrared (15 sec)	220°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 4. Truth Table

ADG441/ADG444 IN	ADG442 IN	Switch Condition
0	1	ON
1	0	OFF

#### **ESD CAUTION**



**ESD** (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

### PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

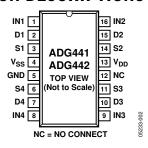


Figure 2. ADG441/ADG442 (DIP/SOIC)

Table 5. ADG441/ADG442 Pin Function Descriptions

Pin No. Mnemonic Description				
Mnemonic	Description			
IN1 to IN4	Logic Control Input.			
D1 to D4	Drain Terminal. May be an input or output.			
S1 to S4	Source Terminal. May be an input or output.			
V <sub>SS</sub>	Most Negative Power Supply Potential in Dual Supplies. In single-supply applications, it may be connected to ground.			
GND	Ground (0 V) Reference.			
NC	No Connect.			
$V_{DD}$	Most Positive Power Supply Potential.			
	D1 to D4 S1 to S4 V <sub>SS</sub> GND NC			

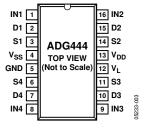


Figure 3. ADG444 (DIP/SOIC)

Table 6. ADG444 Pin Function Descriptions

Pin No.	Mnemonic	Description
1, 8, 9, 16	IN1 to IN4	Logic Control Input.
2, 7, 10, 15	D1 to D4	Drain Terminal. May be an input or output.
3, 6, 11, 14	S1 to S4	Source Terminal. May be an input or output.
4	Vss	Most Negative Power Supply Potential in Dual Supplies. In single-supply applications, it may be connected to ground.
5	GND	Ground (0 V) Reference.
12	V <sub>L</sub>	Logic Power Supply (5 V).
13	$V_{DD}$	Most Positive Power Supply Potential.

### TYPICAL PERFORMANCE CHARACTERISTICS

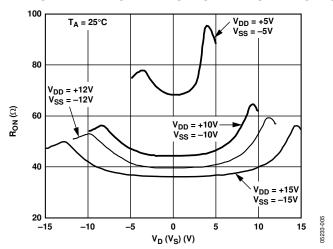


Figure 4.  $R_{ON}$  as a Function of  $V_D$  ( $V_S$ ): Dual Supply

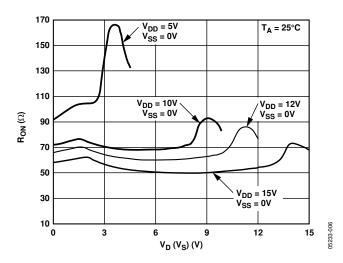


Figure 5.  $R_{ON}$  as a Function of  $V_D$  ( $V_S$ ): Single Supply

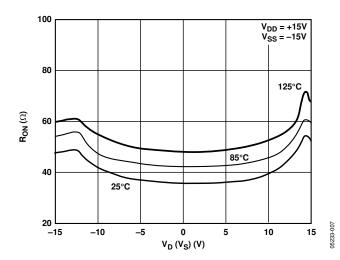


Figure 6.  $R_{ON}$  as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures

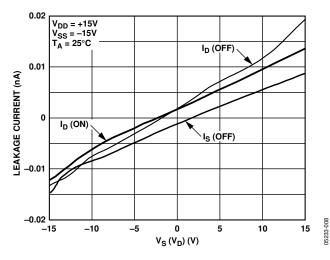


Figure 7. Leakage Currents as a Function of  $V_S(V_D)$ 

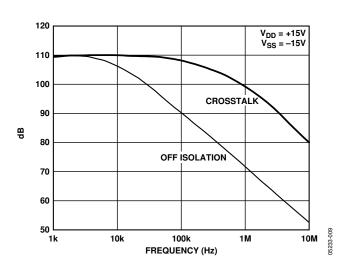


Figure 8. Crosstalk and Off Isolation vs. Frequency

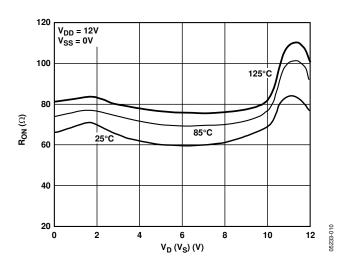


Figure 9.  $R_{ON}$  as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures

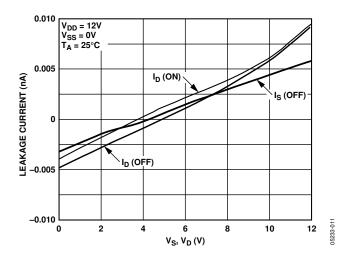


Figure 10. Leakage Currents as a Function of  $V_S$  ( $V_D$ )

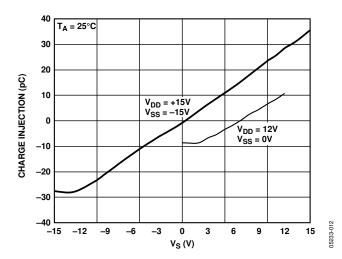


Figure 11. Charge Injection vs. Source Voltage

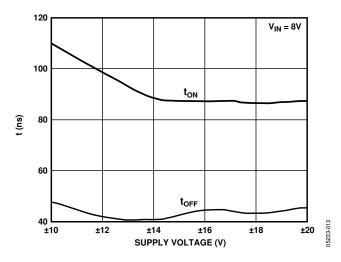


Figure 12. Switching Time vs. Bipolar Supply

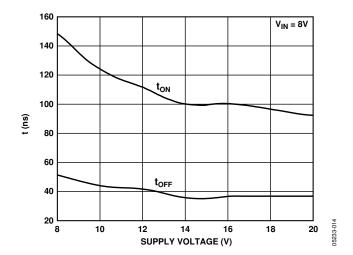
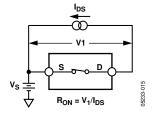
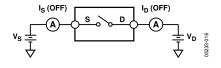


Figure 13. Switching Time vs. Single Supply

## **TEST CIRCUITS**





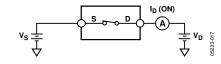


Figure 14. On Resistance

Figure 15. Off Leakage

Figure 16. On Leakage

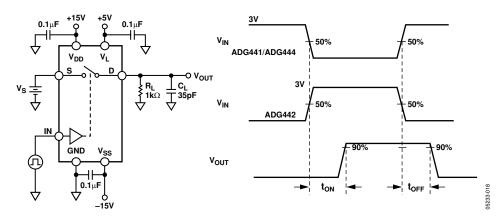


Figure 17. Switching Times

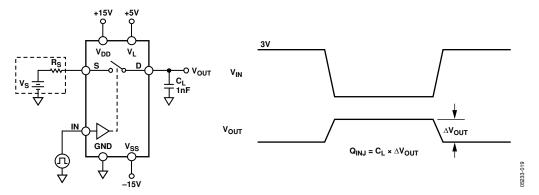


Figure 18. Charge Injection

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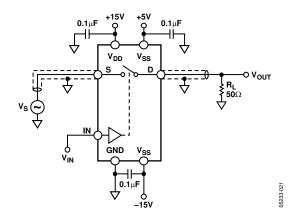


Figure 19. Off Isolation

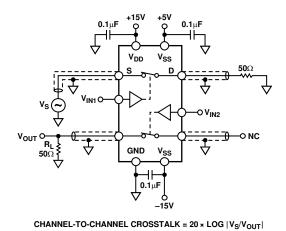


Figure 20. Channel-to-Channel Crosstalk

### **TERMINOLOGY**

 $\mathbf{R}_{\mathbf{ON}}$ 

Ohmic resistance between D and S.

Ron Match

Difference between the Ron of any two channels.

Is (OFF)

Source leakage current with the switch OFF.

I<sub>D</sub> (OFF)

Drain leakage current with the switch OFF.

 $I_D$ ,  $I_S$  (ON)

Channel leakage current with the switch ON.

 $V_D(V_S)$ 

Analog voltage on Terminals D, S.

Cs (OFF)

OFF switch source capacitance.

C<sub>D</sub> (OFF)

OFF switch drain capacitance.

C<sub>D</sub>, C<sub>s</sub> (ON)

ON switch capacitance.

 $t_{ON}$ 

Delay between applying the digital control input and the output switching on.

toff

Delay between applying the digital control input and the output switching off.

 $t_{OPEN}$ 

Break-before-make delay when switches are configured as a multiplexer.

Crosstalk

A measure of unwanted signal which is coupled through from one channel to another as a result of parasitic capacitance.

Off Isolation

A measure of unwanted signal coupling through an OFF switch.

**Charge Injection** 

A measure of the glitch impulse transferred from the digital input to the analog output during switching.

### TRENCH ISOLATION

In the ADG441A, ADG442A, and ADG444A, an insulating oxide layer (trench) is placed between the NMOS and the PMOS transistors of each CMOS switch. Parasitic junctions, which occur between the transistors in junction isolated switches, are eliminated, and the result is a completely latch-up proof switch.

In junction isolation, the N and P wells of the PMOS and NMOS transistors form a diode that is reverse-biased under normal operation. However, during overvoltage conditions, this diode becomes forward-biased. A silicon-controlled rectifier (SCR) type circuit is formed by the two transistors causing a significant amplification of the current which, in turn, leads to latch-up. With trench isolation, this diode is removed, and the result is a latch-up proof switch.

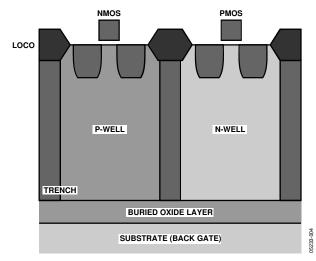
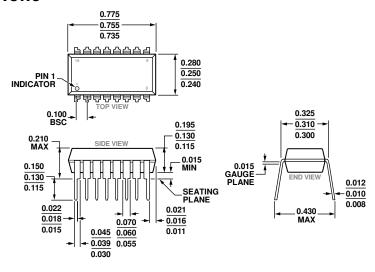


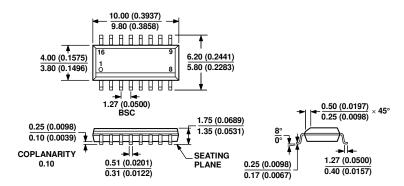
Figure 21. Trench Isolation

### **OUTLINE DIMENSIONS**



#### COMPLIANT TO JEDEC STANDARDS MS-001-BB

Figure 22. 16-Lead Plastic Dual In-Line Package [PDIP] Narrow Body (N-16) Dimensions shown in inches



#### COMPLIANT TO JEDEC STANDARDS MS-012-AC

CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

Figure 23. 16-Lead Standard Small Outline Package [SOIC\_N] (R-16) Dimensions shown in millimeters and (inches)

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#### **ORDERING GUIDE**

Model <sup>1, 2</sup>	Temperature Range	Package Description	Package Option
ADG441BNZ	−40°C to +85°C	16-Lead Plastic Dual In-Line Package [PDIP]	N-16
ADG441BR	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441BR-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441BRZ	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441BRZ-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441ABCHIPS		DIE	
ADG441ABR-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG441ABRZ-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG442BNZ	-40°C to +85°C	16-Lead Plastic Dual In-Line Package [PDIP]	N-16
ADG442BRZ	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG442BRZ-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG444BNZ	−40°C to +85°C	16-Lead Plastic Dual In-Line Package [PDIP]	N-16
ADG444BR	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG444BR-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG444BRZ	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16
ADG444BRZ-REEL	-40°C to +85°C	16-Lead Standard Small Outline Package [SOIC_N]	R-16

 $<sup>^{1}</sup>$  Z = RoHS Compliant Part.  $^{2}$  A = Trench isolated.

**Data Sheet** 

ADG441/ADG442/ADG444

## **NOTES**

## **NOTES**